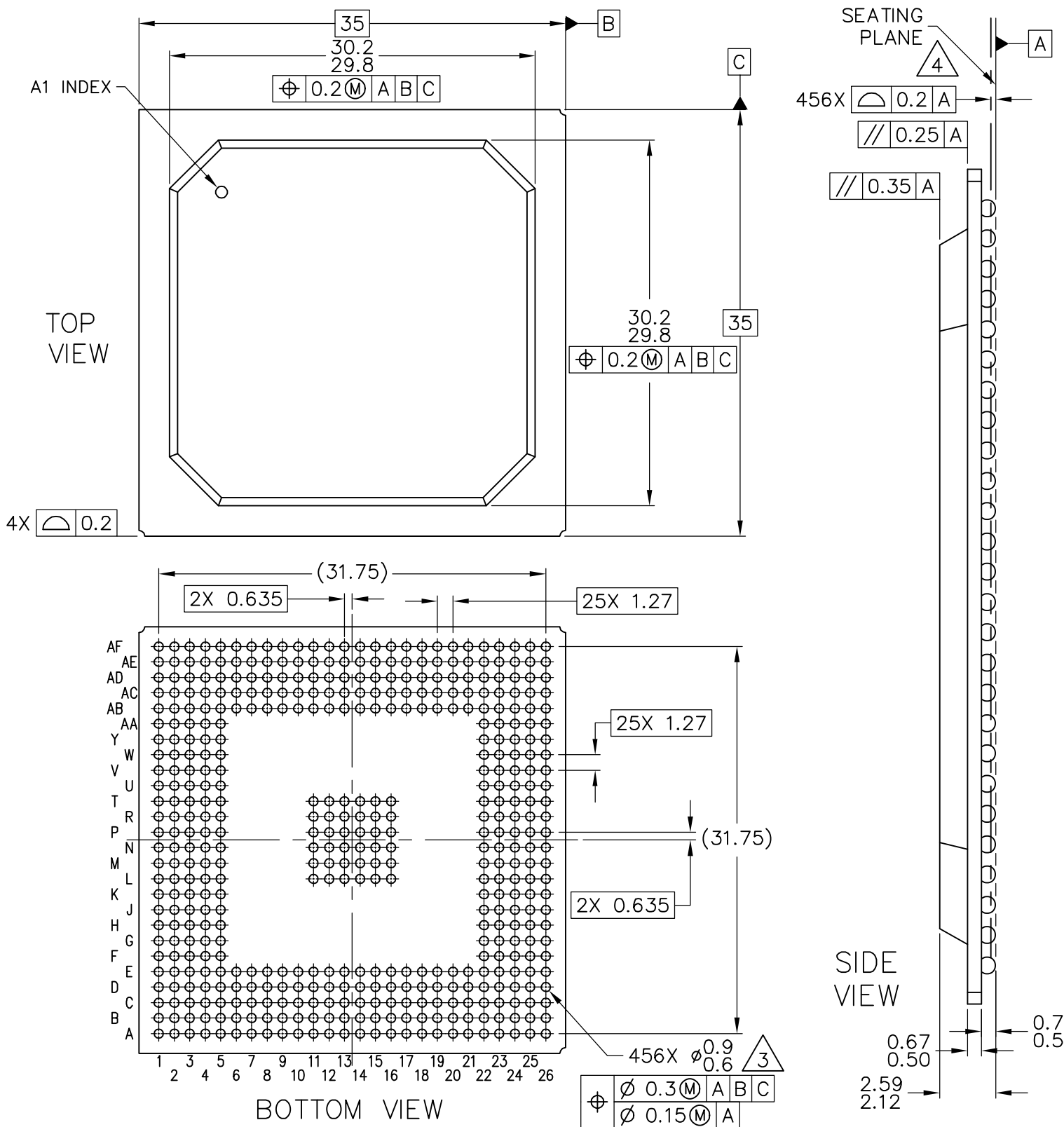




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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: 456 I/O PBGA
35 X 35 PKG,
1.27 MM PITCH

DOCUMENT NO: 98ARS10501D

REV: A

CASE NUMBER: 1397-01

27 MAY 2005

STANDARD: JEDEC MS-034 BAR-2

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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